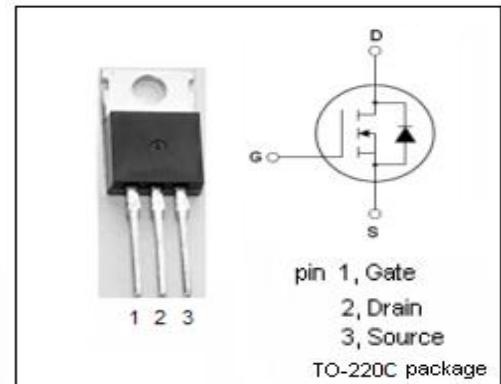


isc N-Channel MOSFET Transistor

2SK1350

DESCRIPTION

- Drain Current – $I_D=15A$ @ $T_c=25^\circ C$
- Drain Source Voltage-
 - : $V_{DSS}=200V$ (Min)
- Fast Switching Speed
- Minimum Lot-to-Lot variations for robust device performance and reliable operation



APPLICATIONS

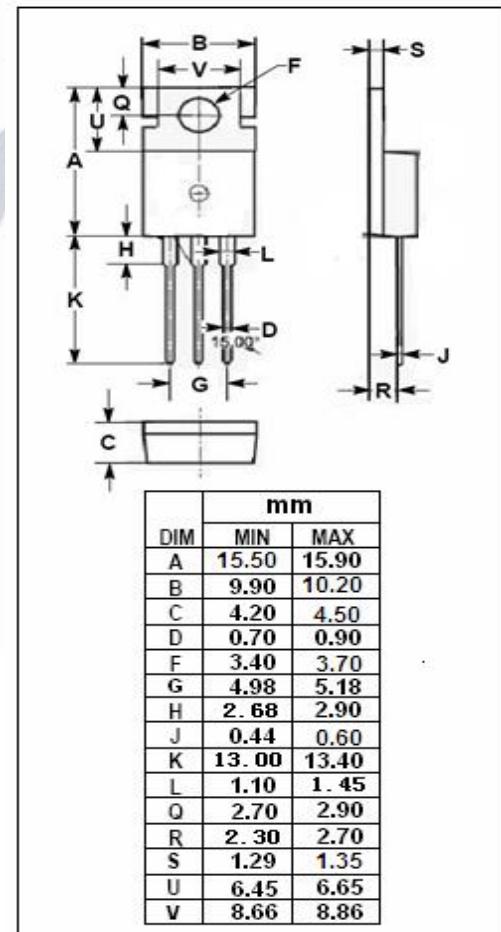
- high speed power switching

ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ C$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage ($V_{GS}=0$)	200	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-continuous@ $TC=25^\circ C$	15	A
P_{tot}	Total Dissipation@ $TC=25^\circ C$	125	W
T_j	Max. Operating Junction Temperature	150	°C
T_{stg}	Storage Temperature Range	-55~150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th\ j-c}$	Thermal Resistance,Junction to Case	1.0	°C/W
$R_{th\ j-a}$	Thermal Resistance,Junction to Ambient	62	°C/W



isc N-Channel Mosfet Transistor**2SK1350****• ELECTRICAL CHARACTERISTICS ($T_c=25^\circ\text{C}$)**

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0$; $I_D=10\text{mA}$	200			V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=10$ V; $I_D=1\text{mA}$	1.5		3.5	V
$R_{DS(\text{on})}$	Drain-Source On-stage Resistance	$V_{GS}=10\text{V}$; $I_D=10\text{A}$		0.1 4	0.18	Ω
I_{GSS}	Gate Source Leakage Current	$V_{GS} = \pm 20\text{V}$; $V_{DS}=0$			± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=200\text{V}$; $V_{GS}=0$			300	uA
V_{SD}	Diode Forward Voltage	$I_F=15\text{A}$; $V_{GS}=0$			2.0	V
t_r	Rise time	$V_{GS}=10\text{V}$; $I_D=10\text{A}$; $R_L=10\Omega$		30	60	ns
t_{on}	Turn-on time			45	90	ns
t_f	Fall time			30	60	ns
t_{off}	Turn-off time			70	140	ns